



NEWS RELEASE

Credo to Contribute OmniConnect Scale-In Interconnect Solution to the Open Compute Project to Address AI Inference Memory Wall

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Enabling an Open Ecosystem of OmniConnect Products from Credo and Third Parties Based on Standardized Interconnect to Alleviate Dependence on High-Bandwidth Memory (HBM)

SAN JOSE, Calif.--(BUSINESS WIRE)-- **Credo Technology Group Holding Ltd** (Credo) (NASDAQ: CRDO), an innovator in providing connectivity at scale through fast, reliable, and energy-efficient system solutions, today announced its plans to standardize an interconnect within the Open Compute Project (OCP) Community for addressing the memory wall challenge. The memory wall is the gap between how fast processors can compute and how fast memory can supply data, causing expensive compute resources to sit idle waiting for data. In modern AI inference environments, memory bandwidth and capacity—not compute power—are often the dominant constraints on system performance.

Credo has formed the OCP Open Chiplet Economy (OCE) Lightweight Serial Interconnect (LSI) Workstream to develop interconnect solutions to overcome the memory bottlenecks that limit AI inference scalability in data infrastructure. In combination with the creation of the OCE LSI Workstream, Credo intends to contribute its OmniConnect lightweight AXI framer specification to OCP, with the goal to advance an open ecosystem of OmniConnect products from Credo and third parties that enable memory disaggregation and chip-to-chip communications.

and memory access speeds.

News Highlights:

- Credo plans to standardize an interconnect within the Open Compute Project (OCP) Community to help address the memory wall, the growing gap between processor performance

- Credo has established the OCP Open Chiplet Economy (OCE) Lightweight Serial Interconnect (LSI) Workstream and plans to contribute its OmniConnect lightweight AXI framer specification.
- The initiative aims to reduce dependence on costly, capacity-constrained HBM by enabling composable AI architectures that can deliver up to 25x greater memory density and 5% higher bandwidth than HBM4.
- Credo is helping to create an open, interoperable ecosystem for memory disaggregation and chip-to-chip communications.

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High-Bandwidth Memory (HBM) suffers from very high cost, limited availability, and density issues. The standardization of a lightweight, high-efficiency serial interconnect option promotes the flexible composition of chiplet-based and modular AI systems and reduces reliance on HBM. AI system designers can flexibly compose domain-specific architectures optimized for diverse and evolving AI models, data flows, and workload characteristics, enabling up to 25x increase in memory density and 5% increase in bandwidth compared to HBM4. The effort supports the broader industry transition toward composable infrastructure—where compute, memory, and storage can be optimally combined—helping unlock higher performance, better resource utilization, and greater cost efficiency for AI at scale.

“We formed the OCP LSI Workstream to address a clear industry need for innovative interconnect solutions that address the memory wall problem while also enabling a new generation of high-bandwidth and power-optimized modular architectures for AI systems,” said Vishal Shah, Vice President of Product, Credo. “Advancing an open approach to lightweight framing and serial interconnect is critical to enabling flexible chiplet integration, including near-package pluggable configurations, for the next wave of AI inference.”

“We welcome Credo’s leadership in helping to define open frameworks and standards that can accelerate innovation and scalability across the ecosystem with the OCP LSI Workstream,” said Anu Ramamurthy, Co-Lead, OCP Open Chiplet Economy Subproject. “Credo’s intended contribution of the lightweight AXI framer specification to OCP is an important step toward aligning the industry around AI interconnect architectures that enable interoperability, reduce complexity and support the high-performance requirements of next-generation AI infrastructure.”

The Lightweight Serial Interconnect (LSI) Workstream operates within the OCP Open Chiplet Economy Subproject,

under the Server Project. More information on the LSI Workstream can be found [here](#).

Credo's intended contribution to OCP of its OmniConnect lightweight AXI framer specification is part of Credo's OmniConnect versatile AXI-over-VSR (Very Short Reach) SerDes bus that enables both die-to-die interconnect and scale-up networking by connecting multiple compute engines via external chipllets. For more information on Credo OmniConnect, visit the product page linked [here](#).

About Credo

Credo's mission is to transform connectivity at scale through fast, reliable, and energy-efficient system solutions. Our high-speed copper and optical interconnect products deliver industry-leading power and performance at up to 1.6T to meet the ever-expanding data infrastructure demands of AI.

Our product portfolio includes ZeroFlap (ZF) Active Electrical Cables (AECs) and ZF optical transceivers, OmniConnect memory solutions, and a suite of retimers and DSPs for optical and copper Ethernet and PCIe, all leveraging the PILOT diagnostic and analytics software platform. Credo innovations enable our customers to connect the systems that connect the world.

For more information, please visit <https://www.credosemi.com>. Follow Credo on [LinkedIn](#).

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